

/ Descriptions

TO-263 N MOS N-CHANNEL MOSFET in a TO-263 Plastic Package.

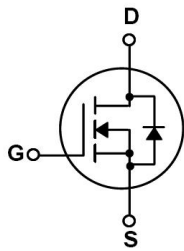
/ Features

Low gate charge, low crss, fast switching.

/ Applications

DC/DC

These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies.

/ Equivalent Circuit**/ Pinning**

PIN1 G PIN 2,4 D PIN 3 S

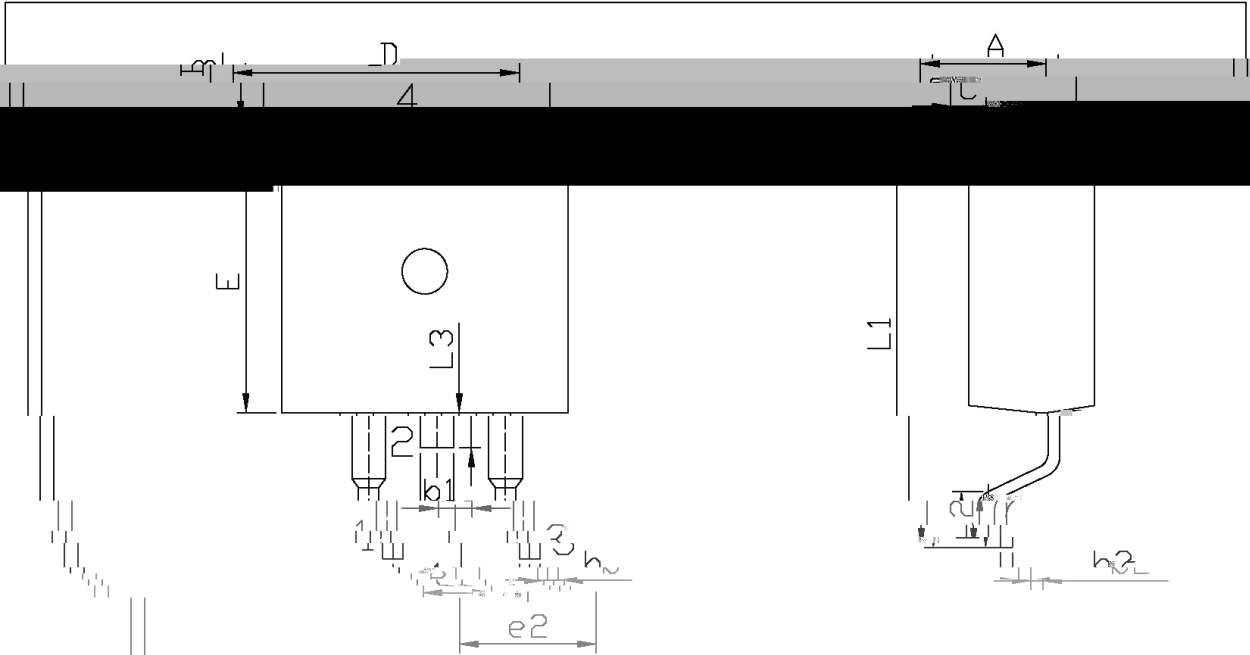
/ h_{FE} Classifications & Marking

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	500	V
Drain Current	$I_D(T_c=25\text{ }^{\circ}\text{C})$	8.0	A
Drain Current	$I_D(T_c=100\text{ }^{\circ}\text{C})$	5.1	A

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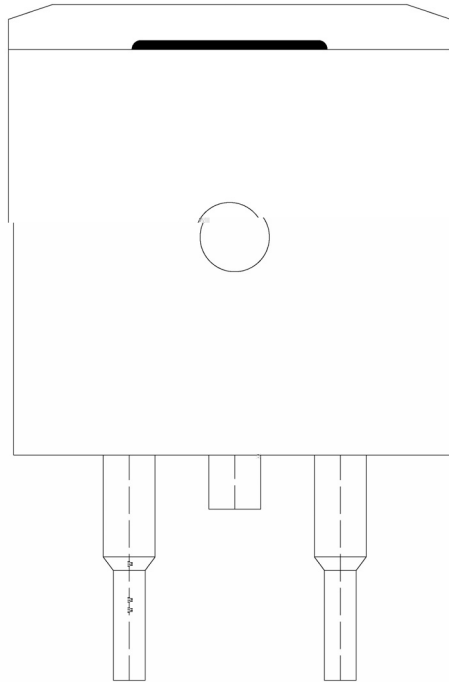
/ Package Dimensions



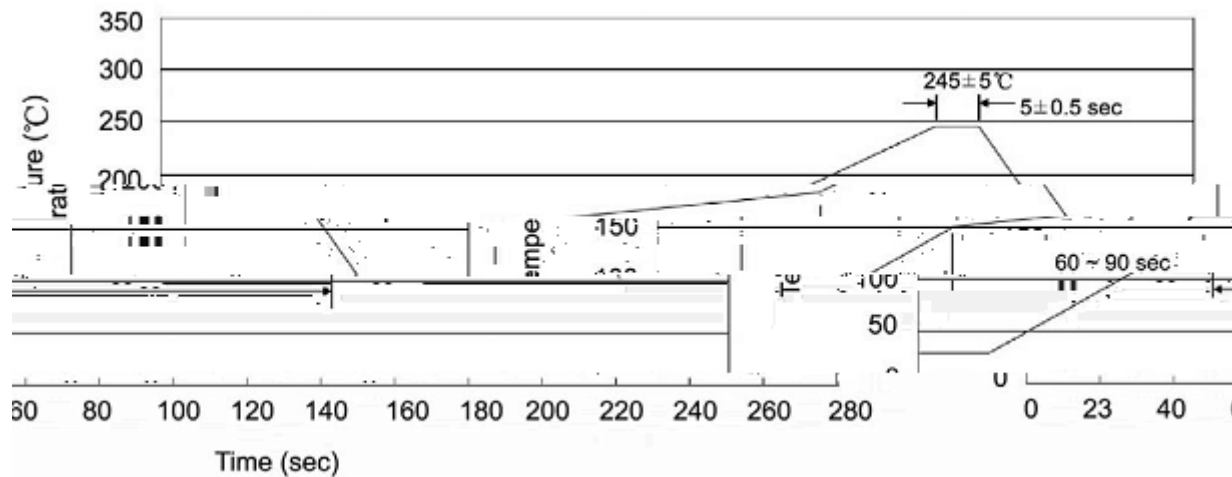
单位: mm

DIMENSIONS IN MILLIMETERS		DIMENSIONS IN INCHES	
Max	Min	Max	Min
9.40	A	4.30	4.70
2.74	B	1.00	1.40
0.80	C	0.80	0.80
0.80	D	0.80	0.80
0.80	E	0.80	0.80
0.80	L1	0.80	0.80
0.80	L2	0.80	0.80
0.80	L3	0.80	0.80
0.80	e1	0.80	0.80
0.80	e2	0.80	0.80
0.80	h1	0.80	0.80
0.80	h2	0.80	0.80
0.80	h3	0.80	0.80
0.80	h4	0.80	0.80

/ Marking Instructions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-263	800	1	800	5	4,000	13 ×24	360×360×50	385×257×392